

Title (en)
LEADFRAME INTERPOSER

Title (de)
LEADFRAME INTERPOSER

Title (fr)
INTERPOSEUR DE GRILLE DE CONNEXION

Publication
EP 1256131 A1 20021113 (DE)

Application
EP 01913532 A 20010125

Priority
• DE 0100283 W 20010125
• DE 10006445 A 20000214

Abstract (en)
[origin: WO0159840A1] The invention relates to a leadframe interposer provided with an upset which is formed by an elevated section in a middle area, and the vertical dimensions of the interposer are enlarged there so that when assembling a housing stack consisting of a number of semiconductor chips, the elevated section presses against an upper side or lower side of a chip housing thereby exerting a compensating turning moment onto the interposer which prevents a possible twisting or deformation from occurring when applying the connecting conductors to the laterally offset contact regions of the interposer.

IPC 1-7
H01L 23/495; **H01L 25/10**

IPC 8 full level
H01L 23/495 (2006.01); **H01L 25/10** (2006.01)

CPC (source: EP US)
H01L 23/495 (2013.01 - EP US); **H01L 25/105** (2013.01 - EP US); **H01L 2225/1029** (2013.01 - EP US); **H01L 2225/107** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

C-Set (source: EP US)
H01L 2924/0002 + **H01L 2924/00**

Citation (search report)
See references of WO 0159840A1

Designated contracting state (EPC)
AT DE FR GB IT

DOCDB simple family (publication)
WO 0159840 A1 20010816; DE 10006445 A1 20010823; DE 10006445 C2 20020328; EP 1256131 A1 20021113; US 2003027437 A1 20030206; US 6652291 B2 20031125

DOCDB simple family (application)
DE 0100283 W 20010125; DE 10006445 A 20000214; EP 01913532 A 20010125; US 21870502 A 20020814